

<p style="text-align: center;">U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE</p> <p style="text-align: center;">LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)</p> <p><i>OTPE SC183 AUG 13 2001</i></p> <p><i>PATENT & TRADEMARK OFFICE</i></p>					ATTY. DOCKET NO. MI22-1599	SERIAL NO. 09/820,468	
					APPLICANT Micron Technology, Inc.		
					FILING DATE March 28, 2001	GROUP 2812	
					U.S. PATENT DOCUMENTS		
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>MCL</i>	AA	5,149,615	9/92	Chakravorty et al.			
<i>MCL</i>	AB	5,808,854	9/98	Figura et al.			
<i>MCL</i>	AC	5,559,666	9/96	Figura et al.			
<i>MCL</i>	AD	5,464,786	11/95	Figura et al.			
<i>MCL</i>	AE	5,654,224	8/97	Figura et al.			
<i>MCL</i>	AF	5,266,519	11/93	Iwamoto			
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
<i>MCL</i>	AL	EP 0 923 125 A	6/16/99	EP			Yes
<i>MCL</i>	AM	EP 0 542 262 A	5/19/93	EP			No
	AN						
	AO						
	AP						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
<i>MCL</i>	AR		"Monolithic Integration of 3-D Electroplated Microstructures with Unlimited Number of Levels Using Planarization with a Sacrificial Metallic Mold"; Yoon et al.;				
			IEEE International Micro-Electro Mechanical Systems Conference; 1999; pps. 624 & 627-629.				
	AS						
	AT						
EXAMINER	<i>MCL</i>			DATE CONSIDERED	<i>11/13/03</i>		
<p>"EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant."</p>							